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HUA HONG SEMICONDUCTOR LIMITED

華虹半導體有限公司

(Incorporated in Hong Kong with limited liability)

(Stock Code: 1347)

ACCEPTANCE BY THE SHANGHAI STOCK EXCHANGE OF APPLICATION MATERIALS FOR THE RMB SHARE ISSUE

This announcement is made by Hua Hong Semiconductor Limited (the “**Company**”) pursuant to Rule 13.09 of the Rules Governing the Listing of Securities on The Stock Exchange of Hong Kong Limited (the “**Hong Kong Listing Rules**”) and the Inside Information Provisions under Part XIVA of the Securities and Futures Ordinance (Chapter 571 of the Laws of Hong Kong).

Reference is made to the announcement dated 21 March 2022 in relation to the proposed issue of RMB Shares, the announcement dated 12 May 2022 and circular dated 7 June 2022 in relation to the proposed RMB Share Issue under Specific Mandate and proposed amendments to Articles, the notice of the EGM dated 7 June 2022 and the announcement dated 27 June 2022 in relation to the poll results of the EGM, respectively published by the Company, which contain, among others, matters relating to the RMB Share Issue of the Company. Unless otherwise defined in this announcement, terms used herein shall have the same meanings as defined in such announcements and circular.

The Company has submitted the application materials in respect of the RMB Share Issue, including (among others) the Initial Public Offering of RMB ordinary shares (A Shares) and Listing on the Science and Technology Innovation Board Prospectus (Application Proof) (the “**A Share Prospectus**”), to the Shanghai Stock Exchange, and has recently received a letter of acceptance issued by the Shanghai Stock Exchange regarding the Company’s application for the RMB Share Issue. The A Share Prospectus will be published on the website for the Review and Approval of the Issuance and Listing of Stocks on the Science and Technology Innovation Board of the Shanghai Stock Exchange (上海證券交易所科創板股票發行上市審核網站) (<http://kcb.sse.com.cn>).

The RMB Share Issue is subject to approval by the necessary Regulatory Approvals and thus may or may not proceed. Shareholders and potential investors of the Company should be aware that there is no assurance that the RMB Share Issue will materialise or as to when it may materialise. Shareholders and potential investors of the Company should exercise caution when dealing in the Shares.

Further announcement(s) will be made by the Company in accordance with the Hong Kong Listing Rules and other applicable laws and regulations of any material updates and progress in connection with the RMB Share Issue as and when appropriate. This announcement is for information purposes only and does not and is not intended to constitute any invitation or offer to acquire, purchase or subscribe for the Share(s).

By order of the Board
Hua Hong Semiconductor Limited
Mr. Suxin Zhang
Chairman and Executive Director

Shanghai, PRC, 4 November 2022

As at the date of this announcement, the directors of the Company are:

Executive Directors:

Suxin Zhang (*Chairman*)

Junjun Tang (*President*)

Non-Executive Directors:

Guodong Sun

Jing Wang

Jun Ye

Independent Non-Executive Directors:

Stephen Tso Tung Chang

Kwai Huen Wong, JP

Long Fei Ye